

### REMARKS

This divisional application is filed as a result of the restriction requirement made November 27, 2002 in the parent application under 35 U.S.C. 121.

Claims 1-10 have been canceled. Claims 11-15 remain for examination in this divisional application. Claims 11-15, especially independent claim 11, are clearly patentable over the references applied in the parent application because the references fail to disclose, teach or suggest, at least, the claimed step of reflowing the first and second solder bumps so as to securely attach the IC chip to the substrate and securely attach the heat sink to the IC chip **at the same time**. See the last paragraph of claim 11.

Early examination and favorable indication of allowance are courteously solicited.

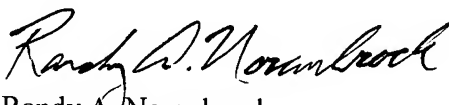
The Examiner is invited to telephone the undersigned, Applicant's attorney of record, to facilitate advancement of the present application.

To the extent necessary, a petition for an extension of time under 37 C.F.R. 1.136 is hereby made. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 07-1337 and please credit any excess fees to such deposit account.

Respectfully submitted,

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